## Abstract

### Method for cleaning a semiconductor wafer

A method for cleaning a facing side and a reverse side of a semiconductor wafer, comprising, in the order given: the cleaning of the facing side of the semiconductor wafer, containing, in the order given: (1) a precleaning step with water, so that the facing side is still wet as the next cleaning step begins, (2) a first cleaning step for cleaning with ozonized water and subsequent rinsing step with purified water, (3) a second cleaning step, which contains a treatment step with ozonized water followed by a treatment step with a liquid containing HF, (4) a third cleaning step for cleaning with ozonized water and subsequent rinsing step with purified water, the joint cleaning of the facing side and the reverse side of the semiconductor wafer, containing: a fourth cleaning step, which contains a treatment step with ozonized water followed by a treatment step with a liquid containing HF, and a drying step, in which both sides of the semiconductor wafer are dried.

Drawing for the Abstract: Figure 1